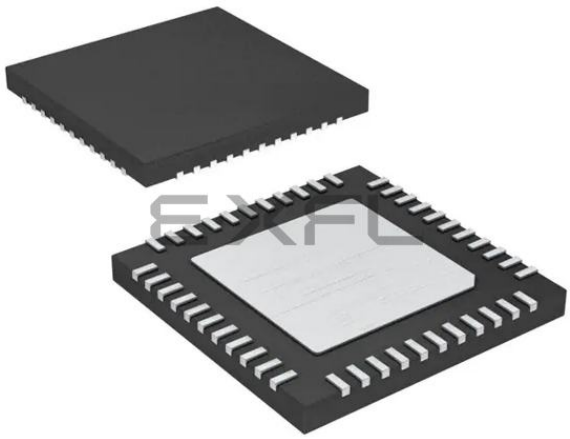
Microchip Technology - DSPIC33FJ64GP804-I/ML Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DCI, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b; D/A 2x16b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64gp804-i-ml

Pin Diagrams (Continued)

44-Pin QFN(2)

■ = Pins are up to 5V tolerant

Note 1: The RPx pins can be used by any remappable peripheral. See Table 1 in this section for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

Referenced Sources

This device data sheet is based on the following individual chapters of the *"dsPIC33F/PIC24H Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note 1: To access the documents listed below, browse to the documentation section of the dsPIC33FJ64GP804 product page of the Microchip web site (www.microchip.com) or select a family reference manual section from the following list.

In addition to parameters, features, and other documentation, the resulting page provides links to the related family reference manual sections.

- **Section 1. "Introduction"** (DS70197)
- **Section 2. "CPU"** (DS70204)
- **Section 3. "Data Memory"** (DS70202)
- **Section 4. "Program Memory"** (DS70203)
- **Section 5. "Flash Programming"** (DS70191)
- **Section 8. "Reset"** (DS70192)
- **Section 9. "Watchdog Timer and Power-Saving Modes"** (DS70196)
- **Section 11. "Timers"** (DS70205)
- **Section 12. "Input Capture"** (DS70198)
- **Section 13. "Output Compare"** (DS70209)
- **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183)
- **Section 17. "UART"** (DS70188)
- **Section 18. "Serial Peripheral Interface (SPI)"** (DS70206)
- **Section 19. "Inter-Integrated Circuit™ (I^2C™)"** (DS70195)
- **Section 23. "CodeGuard™ Security"** (DS70199)
- **Section 24. "Programming and Diagnostics"** (DS70207)
- **Section 25. "Device Configuration"** (DS70194)
- **Section 30. "I/O Ports with Peripheral Pin Select (PPS)"** (DS70190)
- **Section 32. "Interrupts (Part III)"** (DS70214)
- **Section 33. "Audio Digital-to-Analog Converter (DAC)"** (DS70211)
- **Section 34. "Comparator"** (DS70212)
- **Section 35. "Parallel Master Port (PMP)"** (DS70299)
- **Section 36. "Programmable Cyclic Redundancy Check (CRC)"** (DS70298)
- **Section 37. "Real-Time Clock and Calendar (RTCC)"** (DS70301)
- **Section 38. "Direct Memory Access (DMA) (Part III)"** (DS70215)
- **Section 39. "Oscillator (Part III)"** (DS70216)

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip website.

- *"Using MPLAB® ICD 3 In-Circuit Debugger"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 9.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3. Recommendations for crystals and ceramic resonators are provided in Table 2-1 and Table 2-2, respectively.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT

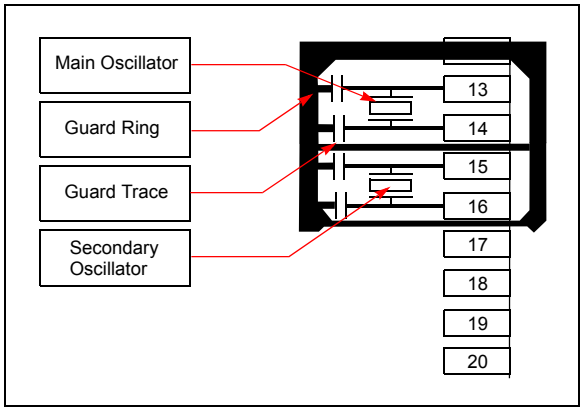


TABLE 2-1: CRYSTAL RECOMMENDATIONS

Part Number	Vendor	Freq.	Load Cap.	Package Case	Frequency Tolerance	Mounting Type	Operating Temperature
ECS-40-20-4DN	ECS Inc.	4 MHz	20 pF	HC49/US	±30 ppm	TH	-40°C to +85°C
ECS-80-18-4DN	ECS Inc.	8 MHz	18 pF	HC49/US	±30 ppm	TH	-40°C to +85°C
ECS-100-18-4-DN	ECS Inc.	10 MHz	18 pF	HC49/US	±30 ppm	TH	-40°C to +85°C
ECS-200-20-4DN	ECS Inc.	20 MHz	20 pF	HC49/US	±30 ppm	TH	-40°C to +85°C
ECS-40-20-5G3XDS-TR	ECS Inc.	4 MHz	20 pF	HC49/US	±30 ppm	SM	-40°C to +125°C
ECS-80-20-5G3XDS-TR	ECS Inc.	8 MHz	20 pF	HC49/US	±30 ppm	SM	-40°C to +125°C
ECS-100-20-5G3XDS-TR	ECS Inc.	10 MHz	20 pF	HC49/US	±30 ppm	SM	-40°C to +125°C
ECS-200-20-5G3XDS-TR	ECS Inc.	20 MHz	20 pF	HC49/US	±30 ppm	SM	-40°C to 125°C
NX3225SA 20MHZ AT-W	NDK	20 MHz	8 pF	3.2 mm x 2.5 mm	±50 ppm	SM	-40°C to 125°C

Legend: TH = Through Hole SM = Surface Mount

TABLE 4-10: UART2 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
U2MODE	0230	UARTEN	—	USIDL	IREN	RTSMD	—	UEN1	UEN0	WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL<1:0>		STSEL	0000
U2STA	0232	UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	0110
U2TXREG	0234	—	—	—	—	—	—	—	UTX8	UART Transmit Register								xxxx
U2RXREG	0236	—	—	—	—	—	—	—	URX8	UART Receive Register								0000
U2BRG	0238	Baud Rate Generator Prescaler																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-11: SPI1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SPI1STAT	0240	SPIEN	—	SPISIDL	—	—	—	—	—	—	SPIROV	—	—	—	—	SPITBF	SPIRBF	0000
SPI1CON1	0242	—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE	SSEN	CKP	MSTEN	SPRE<2:0>			PPRE<1:0>		0000
SPI1CON2	0244	FRMEN	SPIFSD	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	FRMDLY	—	0000
SPI1BUF	0248	SPI1 Transmit and Receive Buffer Register																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-12: SPI2 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SPI2STAT	0260	SPIEN	—	SPISIDL	—	—	—	—	—	—	SPIROV	—	—	—	—	SPITBF	SPIRBF	0000
SPI2CON1	0262	—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE	SSEN	CKP	MSTEN	SPRE<2:0>			PPRE<1:0>		0000
SPI2CON2	0264	FRMEN	SPIFSD	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	FRMDLY	—	0000
SPI2BUF	0268	SPI2 Transmit and Receive Buffer Register																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 7-24: IPC9: INTERRUPT PRIORITY CONTROL REGISTER 9

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	DMA3IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as '0'

bit 2-0 **DMA3IP<2:0>:** DMA Channel 3 Data Transfer Complete Interrupt Priority bits

111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

REGISTER 7-31: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	ILR<3:0>			
bit 15							bit 8

U-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
—	VECNUM<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits
1111 = CPU Interrupt Priority Level is 15
•
•
•
0001 = CPU Interrupt Priority Level is 1
0000 = CPU Interrupt Priority Level is 0

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **VECNUM<6:0>:** Vector Number of Pending Interrupt bits
0111111 = Interrupt Vector pending is number 135
•
•
•
0000001 = Interrupt Vector pending is number 9
0000000 = Interrupt Vector pending is number 8

REGISTER 11-3: RPINR3: PERIPHERAL PIN SELECT INPUT REGISTER 3

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T3CKR<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T2CKR<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **T3CKR<4:0>:** Assign Timer3 External Clock (T3CK) to the corresponding RPn pin
11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **T2CKR<4:0>:** Assign Timer2 External Clock (T2CK) to the corresponding RPn pin
11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

REGISTER 11-7: RPINR11: PERIPHERAL PIN SELECT INPUT REGISTER 11

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	OCFAR<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘0’

bit 4-0 **OCFAR<4:0>:** Assign Output Compare A (OCFA) to the corresponding RPn pin

11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

13.0 TIMER2/3 AND TIMER4/5 FEATURE

Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 11. "Timers"** (DS70205) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

Timer2 and Timer4 are Type B timers with the following specific features:

- A Type B timer can be concatenated with a Type C timer to form a 32-bit timer
- The external clock input (TxCK) is always synchronized to the internal device clock and the clock synchronization is performed after the prescaler.

A block diagram of the Type B timer is shown in Figure 13-1.

Timer3 and Timer5 are Type C timers with the following specific features:

- A Type C timer can be concatenated with a Type B timer to form a 32-bit timer
- At least one Type C timer has the ability to trigger an analog-to-digital conversion.
- The external clock input (TxCK) is always synchronized to the internal device clock and the clock synchronization is performed before the prescaler

A block diagram of the Type C timer is shown in Figure 13-2.

FIGURE 13-1: TYPE B TIMER BLOCK DIAGRAM (x = 2 or 4)

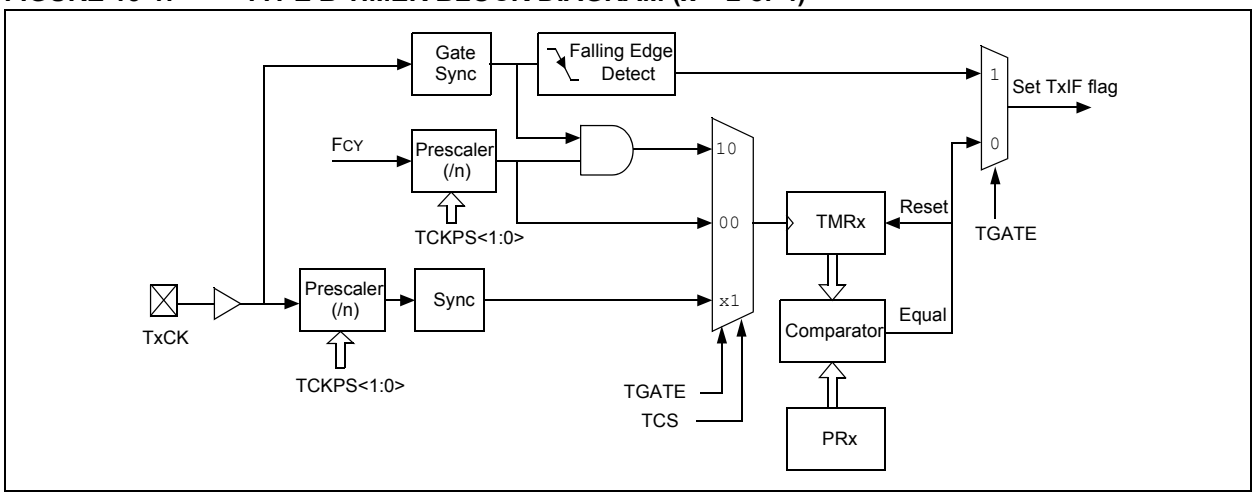


FIGURE 13-2: TYPE C TIMER BLOCK DIAGRAM (x = 3 or 5)

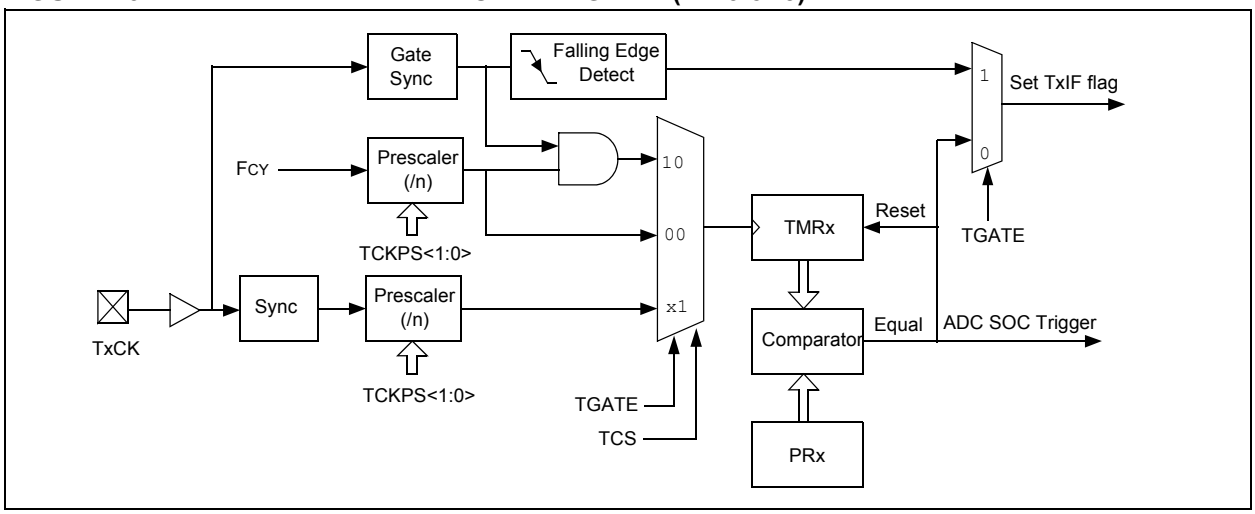
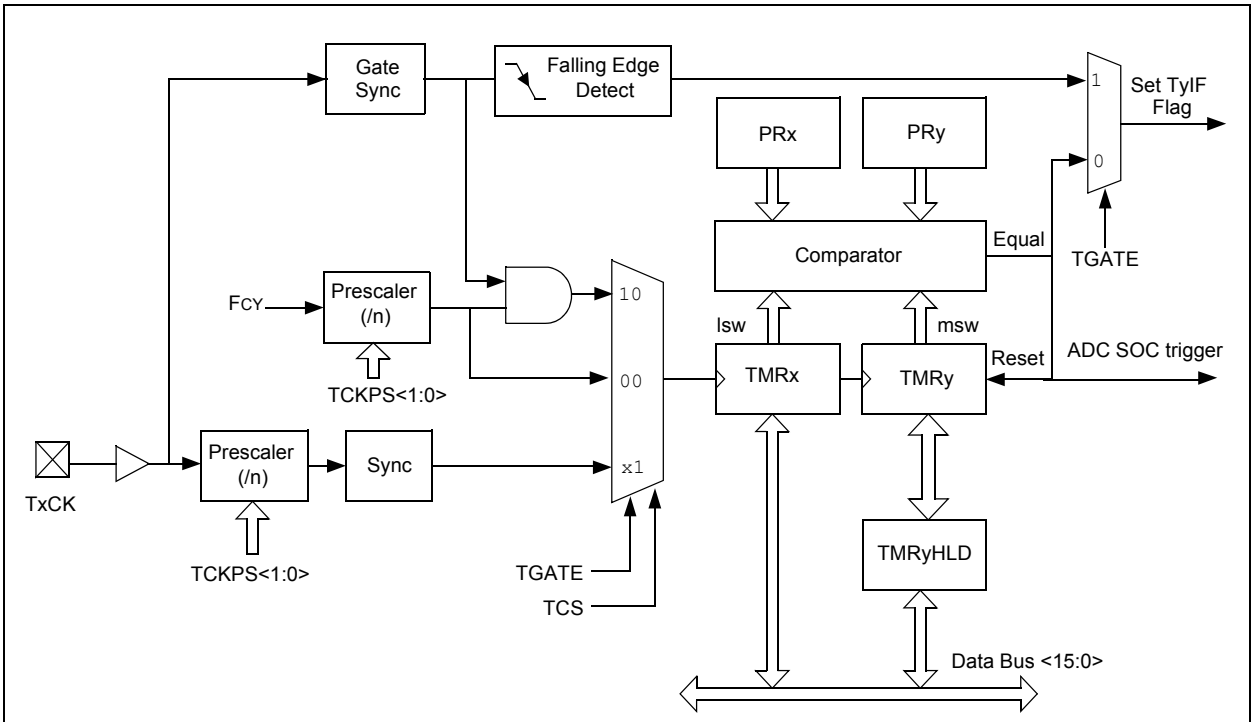


FIGURE 13-3: 32-BIT TIMER BLOCK DIAGRAM



Note 1: ADC trigger is available only on TMR3:TMR2 and TMR5:TMR2 32-bit timers.

2: Timer x is a Type B Timer (x = 2 and 4).

3: Timer y is a Type C Timer (y = 3 and 5).

13.3 Timer Resources

Many useful resources related to Timers are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532311

13.3.1 KEY RESOURCES

- **Section 11. "Timers"** (DS70205)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

REGISTER 17-2: I2CxSTAT: I2Cx STATUS REGISTER

R-0 HSC	R-0 HSC	U-0	U-0	U-0	R/C-0 HS	R-0 HSC	R-0 HSC
ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10
bit 15							bit 8

R/C-0 HS	R/C-0 HS	R-0 HSC	R/C-0 HSC	R/C-0 HSC	R-0 HSC	R-0 HSC	R-0 HSC
IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF
bit 7							bit 0

Legend:	U = Unimplemented bit, read as '0'		C = Clear only bit
R = Readable bit	W = Writable bit	HS = Set in hardware	HSC = Hardware set/cleared
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ACKSTAT:** Acknowledge Status bit
(when operating as I^2C™ master, applicable to master transmit operation)
1 = NACK received from slave
0 = ACK received from slave
Hardware set or clear at end of slave Acknowledge.

bit 14 **TRSTAT:** Transmit Status bit (when operating as I^2C master, applicable to master transmit operation)
1 = Master transmit is in progress (8 bits + ACK)
0 = Master transmit is not in progress
Hardware set at beginning of master transmission. Hardware clear at end of slave Acknowledge.

bit 13-11 **Unimplemented:** Read as '0'

bit 10 **BCL:** Master Bus Collision Detect bit
1 = A bus collision has been detected during a master operation
0 = No collision
Hardware set at detection of bus collision.

bit 9 **GCSTAT:** General Call Status bit
1 = General call address was received
0 = General call address was not received
Hardware set when address matches general call address. Hardware clear at Stop detection.

bit 8 **ADD10:** 10-bit Address Status bit
1 = 10-bit address was matched
0 = 10-bit address was not matched
Hardware set at match of 2nd byte of matched 10-bit address. Hardware clear at Stop detection.

bit 7 **IWCOL:** Write Collision Detect bit
1 = An attempt to write the I2CxTRN register failed because the I^2C module is busy
0 = No collision
Hardware set at occurrence of write to I2CxTRN while busy (cleared by software).

bit 6 **I2COV:** Receive Overflow Flag bit
1 = A byte was received while the I2CxRCV register is still holding the previous byte
0 = No overflow
Hardware set at attempt to transfer I2CxRSR to I2CxRCV (cleared by software).

bit 5 **D_A:** Data/Address bit (when operating as I^2C slave)
1 = Indicates that the last byte received was data
0 = Indicates that the last byte received was device address
Hardware clear at device address match. Hardware set by reception of slave byte.

bit 4 **P:** Stop bit
1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware set or clear when Start, Repeated Start or Stop detected.

20.3 DCI Control Registers

REGISTER 20-1: DCICON1: DCI CONTROL REGISTER 1

R/W-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
DCIEN	—	DCISIDL	—	DLOOP	CSCKD	CSCKE	COFSD
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
UNFM	CSDOM	DJST	—	—	—	COFSM<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **DCIEN:** DCI Module Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **DCISIDL:** DCI Stop in Idle Control bit
1 = Module will halt in CPU Idle mode
0 = Module will continue to operate in CPU Idle mode

bit 12 **Unimplemented:** Read as '0'

bit 11 **DLOOP:** Digital Loopback Mode Control bit
1 = Digital Loopback mode is enabled. CSDI and CSDO pins internally connected.
0 = Digital Loopback mode is disabled

bit 10 **CSCKD:** Sample Clock Direction Control bit
1 = CSCK pin is an input when DCI module is enabled
0 = CSCK pin is an output when DCI module is enabled

bit 9 **CSCKE:** Sample Clock Edge Control bit
1 = Data changes on serial clock falling edge, sampled on serial clock rising edge
0 = Data changes on serial clock rising edge, sampled on serial clock falling edge

bit 8 **COFSD:** Frame Synchronization Direction Control bit
1 = COFS pin is an input when DCI module is enabled
0 = COFS pin is an output when DCI module is enabled

bit 7 **UNFM:** Underflow Mode bit
1 = Transmit last value written to the transmit registers on a transmit underflow
0 = Transmit '0's on a transmit underflow

bit 6 **CSDOM:** Serial Data Output Mode bit
1 = CSDO pin will be tri-stated during disabled transmit time slots
0 = CSDO pin drives '0's during disabled transmit time slots

bit 5 **DJST:** DCI Data Justification Control bit
1 = Data transmission/reception is begun during the same serial clock cycle as the frame synchronization pulse
0 = Data transmission/reception is begun one serial clock cycle after frame synchronization pulse

bit 4-2 **Unimplemented:** Read as '0'

bit 1-0 **COFSM<1:0>:** Frame Sync Mode bits
11 = 20-bit AC-Link mode
10 = 16-bit AC-Link mode
01 = I^2S Frame Sync mode
00 = Multi-Channel Frame Sync mode

22.0 AUDIO DIGITAL-TO-ANALOG CONVERTER (DAC)

Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 33. "Audio Digital-to-Analog Converter (DAC)"** (DS70211) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Audio Digital-to-Analog Converter (DAC) module is a 16-bit Delta-Sigma signal converter designed for audio applications. It has two output channels, left and right to support stereo applications. Each DAC output channel provides three voltage outputs, positive DAC output, negative DAC output, and the midpoint voltage output for the dsPIC33FJ64GP804 and dsPIC33FJ128GP804 devices. The dsPIC33FJ64GP802 and dsPIC33FJ128GP802 devices provide positive DAC output and negative DAC output voltages.

22.1 Key Features

- 16-bit resolution (14-bit accuracy)
- Second-Order Digital Delta-Sigma Modulator
- 256 X Over-Sampling Ratio
- 128-Tap FIR Current-Steering Analog Reconstruction Filter
- 100 ksps Maximum Sampling Rate
- User controllable Sample Clock
- Input Frequency 45 kHz max
- Differential Analog Outputs
- Signal-To-Noise: 90 dB
- 4-deep input Buffer
- 16-bit Processor I/O, and DMA interfaces

22.2 DAC Module Operation

The functional block diagram of the Audio DAC module is shown in Figure 22-1. The Audio DAC module provides a 4-deep data input FIFO buffer for each output channel. If the DMA module and/or the processor cannot provide output data in a timely manner, and the FIFO becomes empty, the DAC accepts data from the DAC Default Data register (DACDFLT). This safety feature is useful for industrial control applications where the DAC output controls an important processor or machinery. The DACDFLT register should be initialized with a "safe" output value. Often the safe output value is either the midpoint value (0x8000) or a zero value (0x0000).

The digital interpolator up-samples the input signals, where the over-sampling ratio is 256x which creates data points between the user supplied data points. The interpolator also includes processing by digital filters to provide "noise shaping" to move the converter noise above 20 kHz (upper limit of the pass band). The output of the interpolator drives the Sigma-Delta modulator. The serial data bit stream from the Sigma-Delta modulator is processed by the reconstruction filter. The differential outputs of the reconstruction filter are amplified by Op Amps to provide the required peak-to-peak voltage swing.

Note: The DAC module is designed specifically for audio applications and is not recommended for control type applications.

22.3 DAC Output Format

The DAC output data stream can be in a two's complement signed number format or as an unsigned number format.

The Audio DAC module features the ability to accept the 16-bit input data in a two's complement signed number format or as an unsigned number format. The data formatting is controlled by the Data Format Control bit (FORM<8>) in the DAC1CON register. The supported formats are:

- 1 = Signed (two's complement)
- 0 = Unsigned

If the FORM bit is configured for "Unsigned data" then the user input data yields the following behavior:

- 0xFFFF = most positive output voltage
- 0x8000 = mid point output voltage
- 0x7FFF = a value just below the midpoint
- 0x0000 = minimum output voltage

If the FORM bit is configured for "signed data" then the user input data yields the following behavior:

- 0x7FFF = most positive output voltage
- 0x0000 = mid point output voltage
- 0xFFFF = value just below the midpoint
- 0x8000 = minimum output voltage

The Audio DAC provides an analog output proportional to the digital input value. The maximum 100,000 samples per second (100 ksps) update rate provides good quality audio reproduction.

26.1 PMP Resources

Many useful resources related to PMP are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532311

26.1.1 KEY RESOURCES

- **Section 35. “Parallel Master Port (PMP)”** (DS70299)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

TABLE 27-5: CODE FLASH SECURITY SEGMENT SIZES FOR 128 KB DEVICES

CONFIG BITS	BSS<2:0> = x11 0K	BSS<2:0> = x10 1K	BSS<2:0> = x01 4K	BSS<2:0> = x00 8K
SSS<2:0> = x11 0K	VS = 256 IW GS = 43776 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh	VS = 256 IW BS = 768 IW GS = 43008 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh	VS = 256 IW BS = 3840 IW GS = 39936 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh	VS = 256 IW BS = 7936 IW GS = 35840 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh
SSS<2:0> = x10 4K	VS = 256 IW SS = 3840 IW GS = 39936 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00ABFEh 0x0157FEh	VS = 256 IW BS = 768 IW SS = 3072 IW GS = 39936 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00ABFEh 0x0157FEh	VS = 256 IW BS = 3840 IW GS = 39936 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00ABFEh 0x0157FEh	VS = 256 IW BS = 7936 IW GS = 35840 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00ABFEh 0x0157FEh
SSS<2:0> = x01 8K	VS = 256 IW SS = 7936 IW GS = 35840 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh	VS = 256 IW BS = 768 IW SS = 7168 IW GS = 35840 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh	VS = 256 IW BS = 3840 IW SS = 4096 IW GS = 35840 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh	VS = 256 IW BS = 7936 IW GS = 35840 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh
SSS<2:0> = x00 16K	VS = 256 IW SS = 16128 IW GS = 27648 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh	VS = 256 IW BS = 768 IW SS = 15360 IW GS = 27648 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh	VS = 256 IW BS = 3840 IW SS = 12288 IW GS = 27648 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh	VS = 256 IW BS = 7936 IW SS = 8192 IW GS = 27648 IW 0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x007FFEh 0x008000h 0x00FFFEh 0x010000h 0x0157FEh

29.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB C Compiler for Various Device Families
  - HI-TECH C for Various Device Families
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
  - MPLAB ICD 3
  - PICkit™ 3 Debug Express
- Device Programmers
  - PICkit™ 2 Programmer
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

29.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

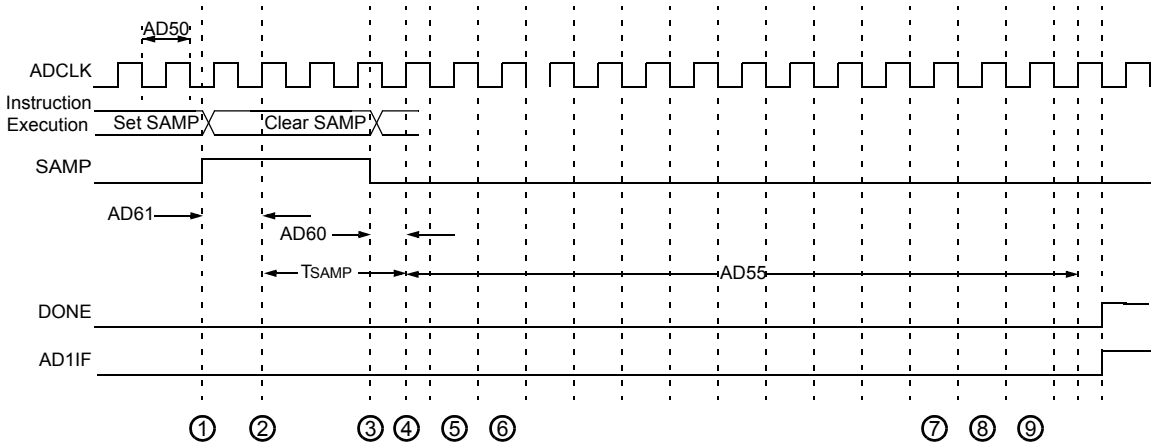
- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - In-Circuit Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
  - Source files (C or assembly)
  - Mixed C and assembly
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

FIGURE 30-24: ADC CONVERSION (12-BIT MODE) TIMING CHARACTERISTICS (ASAM = 0, SSRC<2:0> = 000)



1 – Software sets AD1CON. SAMP to start sampling.

2 – Sampling starts after discharge period. TSAMP is described in S**ection 16. "Analog-to-Digital Converter (ADC)" (DS70183)** in the *"dsPIC33F/PIC24H Family Reference Manual"*.

3 – Software clears AD1CON. SAMP to start conversion.

4 – Sampling ends, conversion sequence starts.

5 – Convert bit 11.

6 – Convert bit 10.

7 – Convert bit 1.

8 – Convert bit 0.

9 – One TAD for end of conversion.

TABLE 31-6: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - RA2, RA7-RA10, RB10, RB11, RB7, RB4, RC3-RC9	—	—	0.4	V	IOL ≤1.8 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA0, RA1, RB0-RB3, RB5, RB6, RB8, RB9, RB12-RB15, RC0-RC2	—	—	0.4	V	IOL ≤3.6 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - RA3, RA4	—	—	0.4	V	IOL ≤6 mA, VDD = 3.3V See **Note 1**
DO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - RA2, RA7-RA10, RB4, RB7, RB10, RB11, RC3-RC9	2.4	—	—	V	IOL ≥ -1.8 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA0, RA1, RB0-RB3, RB5, RB6, RB8, RB9, RB12-RB15, RC0-RC2	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 8x Source Driver Pins - RA4, RA3	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V See **Note 1**
DO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - RA2, RA7-RA10, RB4, RB7, RB10, RB11, RC3-RC9	1.5	—	—	V	IOH ≥ -1.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -1.85 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -1.4 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA0, RA1, RB0-RB3, RB5, RB6, RB8, RB9, RB12-RB15, RC0-RC2	1.5	—	—	V	IOH ≥ -3.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -3.7 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 8x Source Driver Pins - RA3, RA4	1.5	—	—	V	IOH ≥ -7.5 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -6.8 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.

FIGURE 32-13: TYPICAL FRC FREQUENCY @ V_{DD} = 3.3V

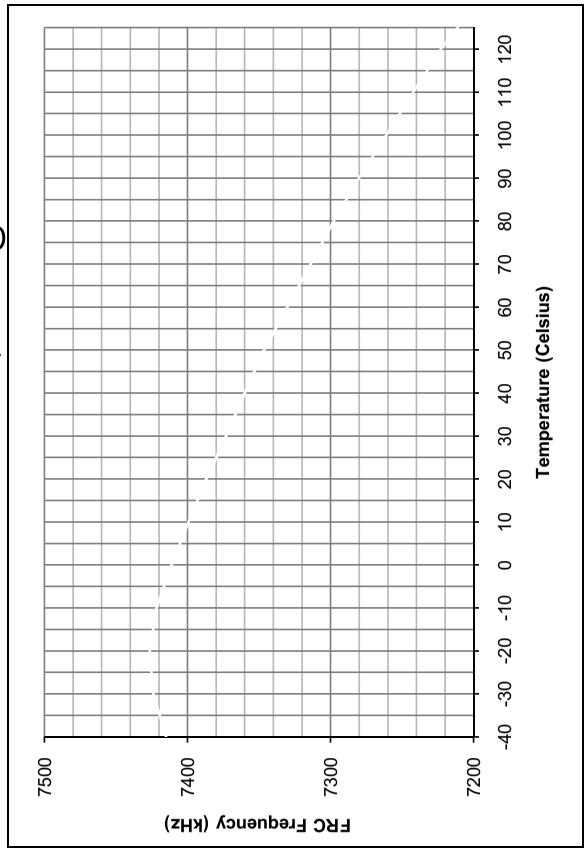
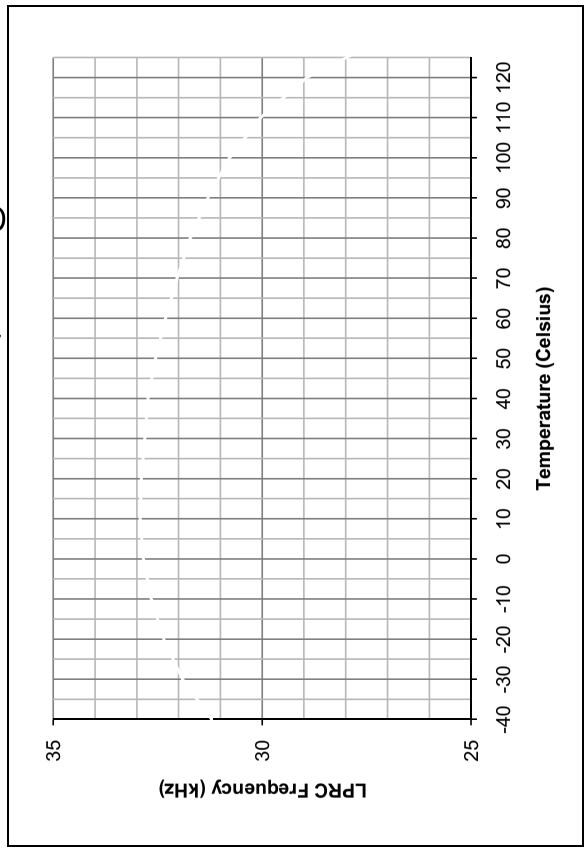


FIGURE 32-14: TYPICAL LPRC FREQUENCY @ V_{DD} = 3.3V



Revision F (August 2011)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE A-5: MAJOR SECTION UPDATES

Section Name	Update Description
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Updated the Recommendation Minimum Connection (see Figure 2-1).
Section 27.0 "Special Features"	Added Note 3 to the Connections for the On-chip Voltage Regulator diagram (see Figure 27-1).
Section 30.0 "Electrical Characteristics"	Removed Voltage on VCAP with respect to Vss from the Absolute Maximum Ratings. Removed Note 3 and parameter DC10 (VCORE) from the DC Temperature and Voltage Specifications (see Table 30-4). Updated the Characteristics definition and Conditions for parameter BO10 in the Electrical Characteristics: BOR (see Table 30-11). Added Note 1 to the Internal Voltage Regulator Specifications (see Table 30-13).

Revision G (April 2012)

This revision includes typographical and formatting changes throughout the data sheet text.

In addition, where applicable, new sections were added to each peripheral chapter that provide information and links to related resources, as well as helpful tips. For examples, see **Section 9.2 "Oscillator Resources"** and **Section 21.4 "ADC Helpful Tips"**.

All other major changes are referenced by their respective section in the following table.

TABLE A-6: MAJOR SECTION UPDATES

Section Name	Update Description
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Added two new tables: • Crystal Recommendations (see Table 2-1) • Resonator Recommendations (see Table 2-2)
Section 30.0 "Electrical Characteristics"	Updated parameters DO10 and DO20 and removed parameters DO16 and DO26 in the DC Characteristics: I/O Pin Output Specifications (see Table 30-10)